

Type	Ag* Al*	V _{DRM} / V _{RRM}	V _{DSM} / V _{RSM} [V]	I _{T(AV)} [A]	Chip Size [mm] x [mm]	Package Options
CWP 71-18	<input checked="" type="checkbox"/> <input checked="" type="checkbox"/>	1800	1900	165	13.40 13.4	sawn on foil <input checked="" type="checkbox"/> unsawn wafer <input checked="" type="checkbox"/> * in waffle pack <input checked="" type="checkbox"/>

*Frontside options

*Please contact IXYS chip sales

Mechanical Parameters

Area active	1.11	cm ²
Area total	1.80	cm ²
Wafer size Ø	150	mm
Thickness	380	µm
Material	Si	
Max. possible chips per wafer	76	
Passivation front side	Glassivation	
Metallization top side	solderable: Ti / Ni / Ag *	
top side	bondable: Al	
Recom. wire bonds (Al)	Cathode	Gate
* = <i>Stitchbonds</i> Number / Ø [µm]	16* / 500	1 / 500
Metallization backside	solderable (only): Ti / Ni / Ag *	
Reject Ink Dot Size	Ø 0.4-1.0 mm	
Recom. Storage Environment		
sawn on foil	in org. container, in dry nitrogen	< 6 month
unsawn wafer	in org. container, in dry nitrogen	< 2 year
in waffle pack	in org. container, in dry nitrogen	< 2 year
T _{stg}	-40 ...	40 °C

Features

- planar design (non-mesa)
- ultra rugged for easy assembly (flat backside)
- excellent long term stability
- very low leakage current
- very low forward voltage drop

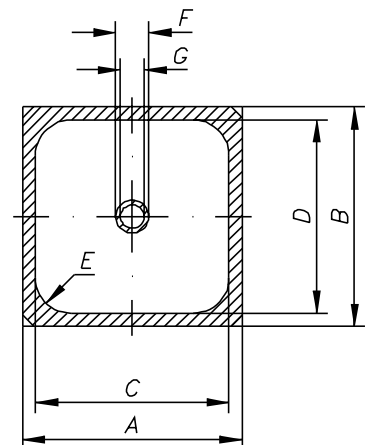
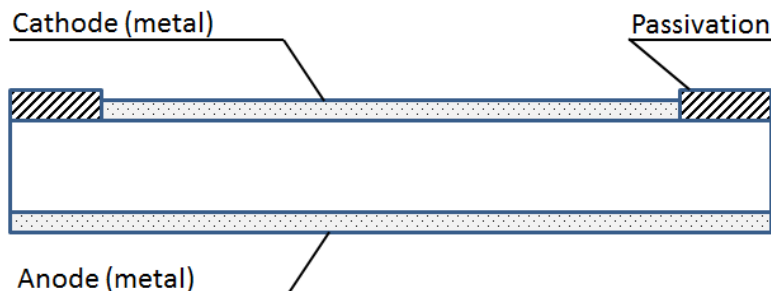
Applications

- DC motor control
- AC power control
- Softstart AC motor controller
- Light, heat and temperature control
- Solid state relays
- Controlled rectifier circuits

*Sinterable top/bottom side on request

Dimensions

A	B	C	D	E	F	G
[mm]	[mm]	[mm]	[mm]	[mm]	[mm]	[mm]
13.40	13.40	10.80	10.80	0.50	2.30	1.50



Electrical parameters

Symbol	Conditions	Ratings		
		min.	typ.	max.
I_R	$V_D = V_R = V_{RR}$ $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 150^\circ\text{C}$			0.1 mA 20 mA
V_T	$I_T = 300\text{ A}$ $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 150^\circ\text{C}$			1.33 V 1.35 V
V_{T0}	For power-loss calculations only			0.89 V
r_T	$T_{VJ} = 150^\circ\text{C}$			1.50 m Ω
V_{GT}	$V_D = 6\text{ V}$ $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$			1.5 V 1.6 V
I_{GT}	$V_D = 6\text{ V}$ $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$	27		150 mA 200 mA
V_{GD}	$T_{VJ} = 150^\circ\text{C}$ $V = \frac{2}{3} V_{DRM}$			0.2 V
I_{GD}				10 mA
I_L	$t_p = 10\ \mu\text{s}$ $T_{VJ} = 25^\circ\text{C}$ $I_G = 0.45\text{ A}$ $di_G/dt = 0.45\text{ A}/\mu\text{s}$			450 mA
I_H	$R_{GK} = \infty$ $T_{VJ} = 25^\circ\text{C}$ $V_D = 6\text{ V}$			200 mA
t_{gd}	$V_D = \frac{1}{2} V_{DRM}$ $T_{VJ} = 25^\circ\text{C}$ $I_G = 0.5\text{ A}$ $di_G/dt = 0.5\text{ A}/\mu$			2 μs
t_q	$V_R = 100\text{ V}$ $I_T = 165\text{ A}$ $-di/dt = 10\text{ A}/\mu\text{s}$ $t_p = 200\ \mu\text{s}$ $dv/dt = 20\text{ V}/\mu\text{s}$ $V_D = \frac{2}{3} V_{DRM}$ $T_{VJ} = 125^\circ\text{C}$			185 μs
$(di/dt)_{cr}$	repetitive $I_T = 250\text{ A}$ non repetitive $I_T = 165\text{ A}$ $V = \frac{2}{3} V_{DRM}$ $T_{VJ} = 150^\circ\text{C}$ $di_G/dt = 0.45\text{ A}/\mu\text{s}$ $I_G = 0.45\text{ A}$ $t_p = 200\ \mu\text{s}$ $f = 50\text{ Hz}$			150 A/ μs 500 A/ μs
$(dv/dt)_{cr}$	$T_{VJ} = 150^\circ\text{C}$ $V_{DR} = \frac{2}{3} V_{DRM}$ $R_{GK} = \infty$ method 1 (linear voltage rise)			1000 V/ μs
P_{GM}	$T_{VJ} = 150^\circ\text{C}$ $t_p = 30\ \mu\text{s}$ $t_p = 3E\ \mu\text{s}$			10 W 5 W
P_{GAV}				0.5 W
V_{RGM}				10 V
T_{VJ}		-40		150 $^\circ\text{C}$
$I_{T(AV)}$	$T_C = 100^\circ\text{C}$ 180° rect. $T_{VJ} = \text{ }^\circ\text{C}$ 180° sine			165 A tbd A
I_{TSM}^*	$T_{VJ} = 45^\circ\text{C}$ $t = 10\text{ ms}$ (50) Hz, sine $V_R = 0\text{ V}$ $t = 8.3\text{ ms}$ (60) Hz, sine $T_{VJ} = 150^\circ\text{C}$ $t = 10\text{ ms}$ (50) Hz, sine $V_R = 0\text{ V}$ $t = 8.3\text{ ms}$ (60) Hz, sine			2200 A 2550 A 2150 A 2300 A
I^2t^*	$T_{VJ} = 45^\circ\text{C}$ $t = 10\text{ ms}$ (50) Hz, sine $V_R = 0\text{ V}$ $t = 8.3\text{ ms}$ (60) Hz, sine $T_{VJ} = 150^\circ\text{C}$ $t = 10\text{ ms}$ (50) Hz, sine $V_R = 0\text{ V}$ $t = 8.3\text{ ms}$ (60) Hz, sine			24200 A s^2 26985 A s^2 23113 A s^2 21954 A s^2
R_{thJC}^*	DC current		0.22	K/W

* Data according to assembled product MCC 95

Data according to IEC 60747

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- the conclusion of quality agreements;
- to establish joint measures to ensure application specific product capabilities and notify that IXYS may delivery dependent on the realization of any such measures.